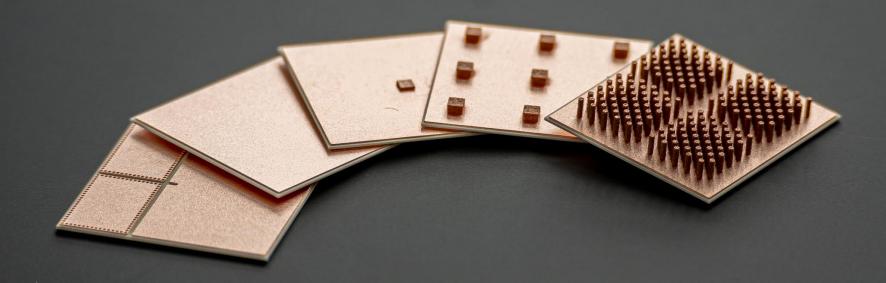


### GlobalAM

Enabling Laser Powder Bed Fusion for Large Scale Production of Multi-Material Components







Metal laser powder bed fusion (LPBF-M) of metals is an established manufacturing technique with great potential in terms of flexibility, digitalization, geometric freedom.

**But:** Productivity of LPBF-M is still too low to penetrate mass markets.

#### Classical AM



Printing massive components

- → Focus: metal on metal substrate
- $\rightarrow$  Cy Hybrid AM
- $\rightarrow$  Cos
- $\rightarrow$  No



Hybrid printing of massive component

- $\rightarrow$  Focus: metal on metal inlay
- → Cy Feature Based Hybrid AM
- $\rightarrow$  Cos
- $\rightarrow$  Fit t

/cm

GlobalAM approach: Focus additive manufacturing on (small) functional elements

Printing tiny features

- $\rightarrow$  Cycle time:  $\sim$  s  $\Psi$
- $\rightarrow$  Powder demand  $\Psi$
- $\rightarrow$  Cost-benefit ratio  $\uparrow$

LPBF-M fits mass manufacturing e.g for electronic components.



GlobalAM aims to unlock the potential of additive manufacturing for large scale production by feature based hybrid production on dissimilar substrate materials.

### **Key Exploitable Results:**



competitive high performance cooling device as industrialization demonstrator



advanced machine concept for highly reduced cycle times + precision positioning of substrates



superior material systems for defect-free products with improved functional performance

#### **Project Key Facts:**



**Project partners** 



36 months **Project duration** 



Jan. 1<sup>st</sup> 2024 Starting date

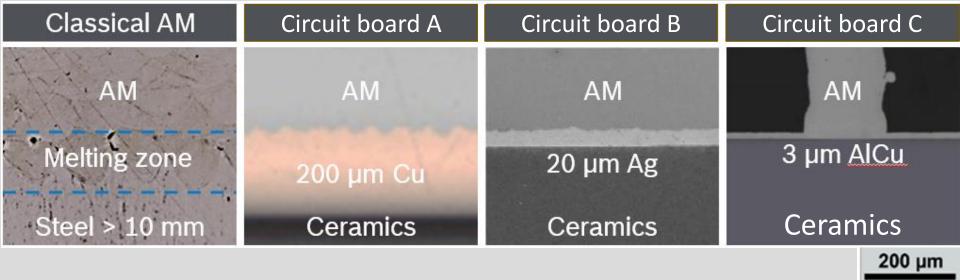


4.0 Mio. € **Budget** 



### GløbalAM Process Challenges

#### Mastering Multi-Material AM on Fragile Substrates



### Challenges

- (1) Multi-material systems: substrate + metalization + AM part
- (2) Strictly limited melting zone: < metalization thickness
- (3) Substrates vulnerable to cracks  $\rightarrow$  low residual stress process

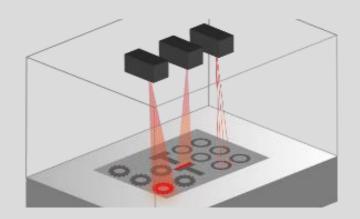
#### **Solutions**

Simulation-supported process development Adapted process strategies

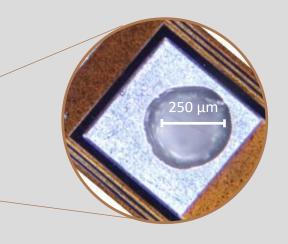


## GløbalAM Machinery Challenges

#### Mastering **Productivity, Precision & Automation**







#### Challenges

- (1) High productivity & cost efficiency
- $\rightarrow$  Short AM cycle times (< 5 min / batch  $\triangleq$  s / part),...
- (2) Highly precise adjustment of laser(s) vs. substrate
- $\rightarrow$  Positional accuracy < 50 µm
- (3) Full line integration automated loading and depowdering

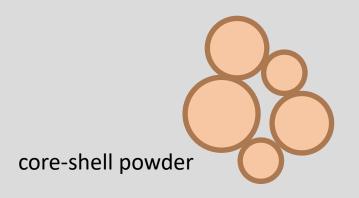
#### **Solutions**

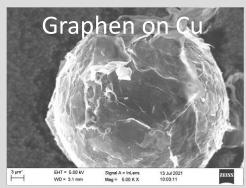
- Laser beam shaping & splitting
- In-line process monitoring and defect compensation
- Substrate fixation & positioning system

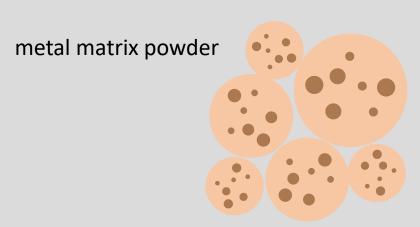


### GløbalAM Materials Challenges

#### Mastering Functional Properties, Aging, Scalability







#### **Challenges**

- (1) Reliably joining of dissimilar materials
- $\rightarrow$  life time requirements for automotive applications
- (2) Best functional properties
- → high flowability/absorption/conductivity, low aging, ...
- (3) Recycling of powder
- → mass production scale powder recycling for economic and environmental compatibility

#### **Solutions**

- core shell powders
- metal matrix composites
- non-standard materials

## GløbalAM Key Enabling Technologies

**Key Enabling Technologies** employed + **responsible partners** to achieve project goals:



#### **Process & Defect Monitoring**

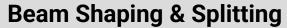
















**BOSCH** 



#### **Substrate Positioning**





#### **In-line Defect Compensation**





**BOSCH** 





#### **Substrate Fixation**





#### **Multi-material Powders**

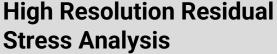






#### **Multi-scale Modelling**





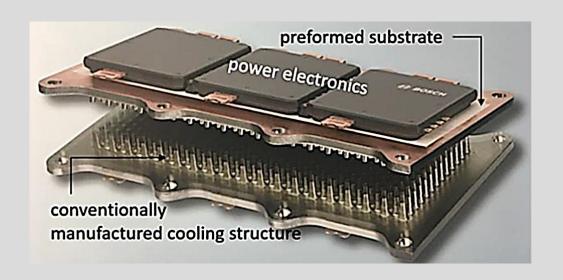






## GløbalAM Inverter Cooler State of the Art

substrate



# cooler chip Cu ceramic long path baseplate

electronics

### **Conventional cooler design**

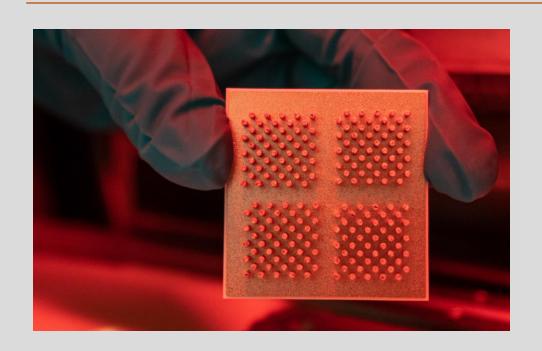
- relatively long cooling path
- soldering/sintering required
- high material usage
- limited design flexibility



- limited cooling performance
- large chip size
- additional assembly effort



### GløbalAM Cooler



# electronics substrate cooler chip Cu short path ceramic

### **GlobalAM** cooler concept

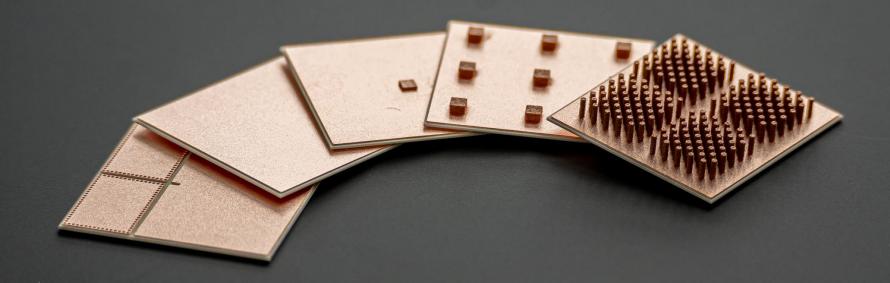
- + minimum cooling path
- + integrated joining process
- + minimum material usage
- + complexity for free



- + high cooling performance
- + reduced chip size
- assembly effort minimized

# GlobalAM

your ace in Laser Powder Bed Fusion.





### Interested in partnering up? Ideas for your applications? Keen to bring in new materials? You are welcome to contact us!



#### **Project Homepage:**

https://www.globalam-project.eu/

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